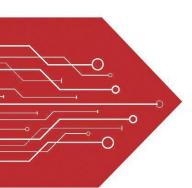
# MSKSEMI















**ESD** 

TVS

**TSS** 

MOV

**GDT** 

**PLED** 

Broduct data speet





# SOD-523

Anode

# **Applications**

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

#### **Features**

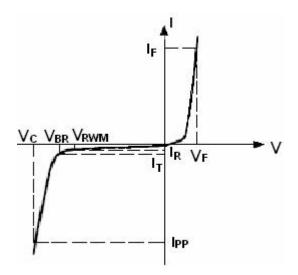
- Small Body Outline Dimensions
- Low Body Height
- Stand-off Voltage: 2.5 V 12 V
- Peak Power up to 200 Watts @ 8 x 20 \_s Pulse
- Low Leakage
- Response Time is Typically < 1 ns
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection
- IEC61000-4-4 Level 4 EFT Protection
- We declare that the material of product compliance with RoHS requirements.
- S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

# Absolute Ratings (T<sub>amb</sub>=25°C)

Symbol	Parameter	Value	Units
P <sub>PP</sub>	Peak Pulse Power (t <sub>p</sub> = 8/20μs)	200	W
TL	Maximum lead temperature for soldering during 10s	260	°C
T <sub>stg</sub>	Storage Temperature Range	-55 to +150	°C
T <sub>op</sub>	Operating Temperature Range	-40 to +125	°C
Tj	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge	±15 ±8	KV
	IEC61000-4-4 (EFT)	40	Α
	ESD Voltage Per Human Body Model	16	KV

# **Electrical Parameter**

Symbol	Parameter
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current
Vc	Clamping Voltage @ IPP
$V_{RWM}$	Working Peak Reverse Voltage
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>
I <sub>T</sub>	Test Current
$V_{BR}$	Breakdown Voltage @ I <sub>T</sub>
I <sub>F</sub>	Forward Current
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>



# **Electrical Characteristics** Ratings at 25°C ambient temperature unless otherwise specified.VF = 0.9V at IF = 10mA

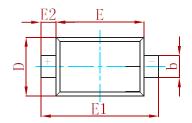
P/N	Marking	V <sub>RWM</sub> (V)	I <sub>R</sub> (uA) @ V <sub>RWM</sub> Max	V <sub>BR</sub> (V)@ I <sub>T</sub> (Note 1) Min	I-	V <sub>C</sub> (V) @ I <sub>PP</sub> =5 A*	V <sub>C</sub> (V) @ Max I <sub>PP</sub> * Max	I <sub>PP</sub> (A)*	P <sub>PK</sub> (W)*	C (pF)
ESD5Z2.5T1G-MS	ZD	2.5	6.0	4.0	1.0	6.5	10.9	11.0	120	145
ESD5Z3.3T1G-MS	ZE	3.3	1.0	5.0	1.0	8.4	14.1	11.2	158	105
ESD5Z5.0T1G-MS	ZF	5.0	1.0	6.2	1.0	11.6	18.6	9.4	174	80
ESD5Z6.0T1G-MS	ZG	6.0	1.0	6.8	1.0	12.4	20.5	8.8	181	70
ESD527.0T1G-MS	ZH	7.0	1.0	7.5	1.0	13.5	22.7	8.8	200	65
ESD5Z12T1G-MS	ZM	12	1.0	13.5	1.0	17	25	9.6	240	55

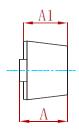
<sup>\*</sup>Surge current waveform per Figure 1.

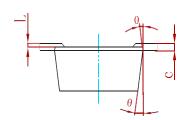
<sup>1.</sup>  $V_{BR}$  is measured with a pluse test current  $I_T$  at an ambient temperature of  $25\,^\circ\!\!\!\mathrm{C}$  .



# PACKAGE MECHANICAL DATA

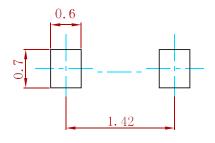






Cumbal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
E	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0.200 REF		0.008 REF		
L	0.010	0.070	0.001	0.003	
0	7° REF		7° REF		

# **Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

# **REEL SPECIFICATION**

P/N	PKG	QTY
ESD5ZXXXT1G-MS	SOD-523	3000



Semiconductor

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